

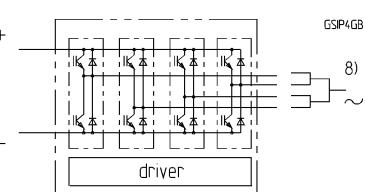
I. Power section

Absolute maximum ratings		$T_s = 25^\circ\text{C}$ unless otherwise specified		
Symbol	Conditions	Values	Units	
IGBT				
$V_{CES}^{(1)}$	Operating DC link voltage	1200 900 ± 20	V V V	
V_{GES}		1200 (900)	A	
I_c	$T_s = 25 \text{ (70) } ^\circ\text{C}$			
Inverse diode				
$I_F = -I_c$	$T_s = 25 \text{ (70) } ^\circ\text{C}$	1200 (900)	A	
I_{FSM}	$T_j = 150 \text{ } ^\circ\text{C}, t_p = 10\text{ms}; \sin$	8640	A	
I^2t (Diode)	Diode, $T_i = 150 \text{ } ^\circ\text{C}, 10\text{ms}$	373	kA ² s	
$T_j, (T_{stg})$		-40 (-25) ...+150 (125)	°C	
V_{isol}	AC, 1min.	3000	V	

Characteristics $T_s = 25^\circ\text{C}$ unless otherwise specified				
Symbol	Conditions	min.	typ.	max.
IGBT				
V_{CEsat}	$I_c = 1000\text{A}, T_j = 25 \text{ (125) } ^\circ\text{C}$	-	2,6 (3,1)	3,1
V_{CEO}	$T_j = 25 \text{ (125) } ^\circ\text{C}$	-	1,2 (1,3)	1,5 (1,6)
r_{CE}	$T_j = 25 \text{ (125) } ^\circ\text{C}$	-	1,3 (1,8)	1,6 (2,0)
I_{CES}	$V_{GE}=0, V_{CE}=V_{CES}, T_j=25(125) \text{ } ^\circ\text{C}$	-	(60)	1,6
$E_{on} + E_{off}$	$I_c=1000\text{A}, V_{cc}=600\text{V}$ $T_j=125^\circ\text{C}$	-	-	300
	$V_{cc}=900\text{V}$	-	-	529
$R_{CC'-EE'}$	terminal chip, $T_j = 125 \text{ } ^\circ\text{C}$	-	0,13	-
L_{CE}	top, bottom	-	3,8	nH
C_{CHC}	per phase, AC-side	-	5,6	nF
Inverse diode				
$V_F = V_{EC}$	$I_F=1000\text{A}; T_j = 25(125) \text{ } ^\circ\text{C}$	-	2,1 (2,0)	2,6
V_{TO}	$T_j = 25 \text{ (125) } ^\circ\text{C}$	-	1,3 (1,0)	1,4 (1,1)
r_T	$T_j = 25 \text{ (125) } ^\circ\text{C}$	-	0,8 (1,0)	1,1 (1,3)
E_{RR}	$I_c=1000\text{A} V_{cc}=600\text{V}$ $T_j=125^\circ\text{C}$	-	-	39
	$V_{cc}=900\text{V}$	-	-	49
Mechanical data				
M_{dc}	DC terminals, SI Units	6	-	8
M_{ac}	AC terminals, SI Units	13	-	15
w	SKiiP® 2 System w/o heat sink	-	3,5	kg
w	heat sink	-	8,5	kg
Thermal characteristics (P16 heat sink; 275 m ³ /h); "r" reference to temperature sensor				
$R_{thjIGBT}$	per IGBT	-	-	0,023
$R_{thjdiode}$	per diode	-	-	0,063
R_{thra}	per module	-	-	0,033
Z_{th}	$R_i \text{ (mK/W) (max.)}$	1 2 3 4	1 2 3 4	tau _i (s)
IGBT _{jr}	2 7	17 48	3 8	0,023 0,063
diode _{jr}	2 7	17 48	3 8	0,001 0,001
heatsink _{ra}	1,6 22,0	7,0 2,4	494 165	20 0,03

SKiiP® 2**SK integrated intelligent Power 2-pack****SKiiP 1242GB120-407CTV**

Case S4

**Features**

- SKiiP technology inside
- low loss IGBTs
- CAL diode technology
- integrated current sensor
- integrated temperature sensor
- integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP® 2 System)
- IEC 68T.1 (climate) 40/125/56 (SKiiP® 2 power section)

1) with assembly of suitable MKP capacitor per terminal (SEMIKRON type is recommended)

8) AC connection busbars must be connected by the user; copper busbars available on request

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SKiiP 1242GB120-407CTV

SKiiP 2®

SK integrated intelligent Power

SKiiP 1242GB120-407CTV

Gate driver features

- CMOS compatible inputs
- wide range power supply
- integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- short circuit protection
- over current protection
- over voltage protection (option)
- power supply protected against under voltage
- interlock of top/bottom switch
- isolation by transformers
- fibre optic interface (option for GB-types only)
- IEC 68T.1 (climate) 25/85/56 (SKiiP® 2 gate driver)

II. Integrated gate driver

Absolute maximum ratings

Symbol	Term	Value	Unit
V_{S1}	stabilized 15V power supply	18	V
V_{S2}	unstabilized 24V power supply	30	V
V_{iH}	input signal voltage (high)	15 + 0,3	V
dv/dt	secondary to primary side	75	kV/μs
V_{isoIO}	input / output (AC)	3000	Vac
V_{isoI2}	output 1 / output 2 (AC)	1500	Vac
f_{max}	switching frequency	14	kHz
$T_{op} (T_{stg})$	operating / storage temperature	- 25 ... + 85	°C

Electrical characteristics ($T_a = 25^\circ C$)

Symbol		Values	
		min typ max.	Units
V_{S1}	supply voltage stabilized	14,4	V
V_{S2}	supply voltage non stabilized	20	V
I_{S1}	$V_{S1} = 15V$	290 + 580*f / f_{max} + 1,3 * (I _{AC} /A)	mA
I_{S2}	$V_{S2} = 24V$	220 + 420*f / f_{max} + 1,0 * (I _{AC} /A)	mA
V_{iT+}	input threshold voltage (High)	11,2	V
V_{iT-}	input threshold voltage (Low)	—	V
R_{in}	input resistance	—	kΩ
$t_{d(on)IO}$	turn-on propagation time (system)	—	μs
$t_{d(off)IO}$	turn-off propagation time (system)	—	μs
$t_pERRRESET$	error memory reset time	9	μs
t_{TD}	top/bottom switch: interlock time	—	μs
$I_{analogOUT}$	8 V corresponds to max. current of 15 V supply voltage (available when supplied with 24V)	—	A
$I_{Vs1outmax}$	output current at pin 12/14	—	mA
I_{AOmax}	logic low output voltage	—	V
V_{ol}	logic high output voltage	—	V
V_{OH}		—	V
I_{TRIPSC}	over current trip level ($I_{analog OUT} = 10V$)	—	A
I_{TRIPLG}	ground fault protection	—	A
T_{tp}	over temperature protection	110	°C
U_{DCTRIP}	trip level of U _{DC} -protection ($U_{analog OUT} = 9V$); (option)	900	V

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